



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**  
**EXPEDITED PROCEDURE PURSUANT**  
**TO 37 CFR §1.116 REQUESTED**  
**Attn: BOX AF**

09/809,181  
503.39864X00

#16  
Response  
J. Maginella  
SEP 26 2002  
RECEIVED  
TECHNOLOGY CENTER 280C

Applicants: **T. SATOH et al.**

Application No.: **09/809,181**

Filing Date: **March 16, 2001**

Title: **SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD  
FOR HIGH RELIABILITY AND PRODUCTION YIELD RATE WITH  
MINIMAL DAMAGE DUE TO APPLICATION OF MECHANICAL  
STRESS AND THERMAL STRESS (AS AMENDED)**

Art Unit: **2815**

Examiner: **Jose R. Diaz**

**RESPONSE AFTER FINAL**

Assistant Commissioner for Patents  
Washington, D.C. 20231

**September 23, 2002**

Sir:

In response to the final Office Action (Paper No. 14) dated May 21, 2002, the following amendments and remarks are submitted in the above-identified application.

Please amend the above-identified application as follows:

**REMARKS**

Claims 1-10 and 28-36 are pending in this application.

Claims 1-10 and 28-36 have been rejected under 35 U.S.C. §102(b) as being anticipated by, or in the alternative, under 35 U.S.C. §103(a) as being obvious over the